

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BFR 93AW H6327	**Issued**	29. August 2013
MA#	MA001094594		
Package	PG-SOT323-3-1	**Weight***	5.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		348	
	non noble metal	tin	7440-31-5	0.001	0.01		90	
	inorganic material	silicon	7440-21-3	0.015	0.26	0.30	2577	3015
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1324	
	non noble metal	copper	7440-50-8	2.617	43.95	44.13	439433	441286
wire	noble metal	gold	7440-57-5	0.008	0.13	0.13	1299	1299
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5304	
	plastics	epoxy resin	-	0.679	11.40		114044	
	inorganic material	silicondioxide	60676-86-0	2.448	41.11	53.04	411088	530436
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22283	22283
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com